

Chemicals contained in products

Package-type

Epson Package name; **PFBGA12U-208 / Halogen free**

JEITA Package name; **(P-TFBGA-208-1212-0.65)**

Solder ball Type; **Lead(Pb) Free**

Weight; **0.28 [g]** *Note1

Part	Subpart	Subpart weight [mg]	Substance name	CAS No.	Content ※2		Application		
					[mg]	[ppm]			
IC Die	IC Die	26.0	Silicon	7440-21-3	26.0	999914	Base material		
			Boron	7440-42-8	0.00005	2	Dopant		
			Phosphorus	7723-14-0	0.00013	5	Dopant		
			Aluminum	7429-90-5	0.0005	20	Metalization		
			Arsenic *Note3	7440-38-2	0.00013	5	Dopant		
			Fluorine *Note3	7782-41-4	0.00005	2	Dopant		
			Titanium *Note3	7440-32-6	0.0005	20	Metalization		
			Tungsten *Note3	7440-33-7	0.0008	30	Metalization		
			Cobalt *Note3	7440-48-4	0.00005	2	Metalization		
	Stress buffer coat	0.52	Polyimide	-	0.52	1000000	Stress buffer coat *Note4		
Package	Substrate	59.2	Glass-cloth	-	10.40	175310	Reinforcement		
			Barium Sulfate	7727-43-7	2.40	40790	Additive		
			Epoxy resin	-	11.70	197180	Base material		
			Acrylate resin	-	3.40	57800	Base material		
			Pigment	-	1.50	25520	Additive		
			Organic filler	-	0.20	3400	Filler		
			Zinc	7440-66-6	0.054	920	Characteristic preserve		
			Chromium	7440-47-3	0.0018	30	Characteristic preserve		
			Copper	7440-50-8	24.80	419050	Copper foil		
			Nickel	7440-02-0	3.80	64000	Plating		
			Gold	7440-57-5	0.96	16000	Plating		
			Die Bonding material	4.20	Epoxy resin	-	2.80	670000	Adhesive
					Acrylic resin	-	1.40	330000	Adhesive
			Solder ball	17.44	Tin	7440-31-5	16.70	957500	Solder ball
	Silver	7440-22-4			0.61	35000	Solder ball		
	Copper	7440-50-8			0.13	7500	Solder ball		
	Bonding Wire	4.60	Gold	7440-57-5	4.60	1000000	Conductor		
	Mold resin	168.04	Epoxy resin	-	8.40	50000	Base material		
			Silica	60676-86-0/-	146.70	873000	Filler		
			Carbon black	1333-86-4	0.34	2000	Coloring agent		
			Hardening chemical(ex:Phenol resin)	-	8.40	50000	Base material		
			Organic phosphorous compound	-	0.80	5000	Hardening accelerator		
			others	-	3.40	20000	Additive		

Regarding the information of chemical substances

*Note1 The weight might be somewhat different depending on an individual built-in IC-chip specification like the size etc.

*Note2 Content data are estimated values based on supplier information and intended levels of content in product.

Actual measurements may vary from these values somewhat.

*Note3 Use or not-use of these substances depends on individual built-in IC-chip specification.

*Note4 The stress buffer coat may not be used depending on the individual model.